



PRODUCT INFORMATION

Customer :	
Device :	Device ID :
Die Size :	Water Material :
Package Type:	No. of Wires :

8L SOIC NB

MATERIAL INFORMATION

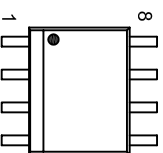
Leadframe :	Pad Size :
Epoxy :	Wire size :
Molding Compound :	Lead Finish :

A194 with spot Ag

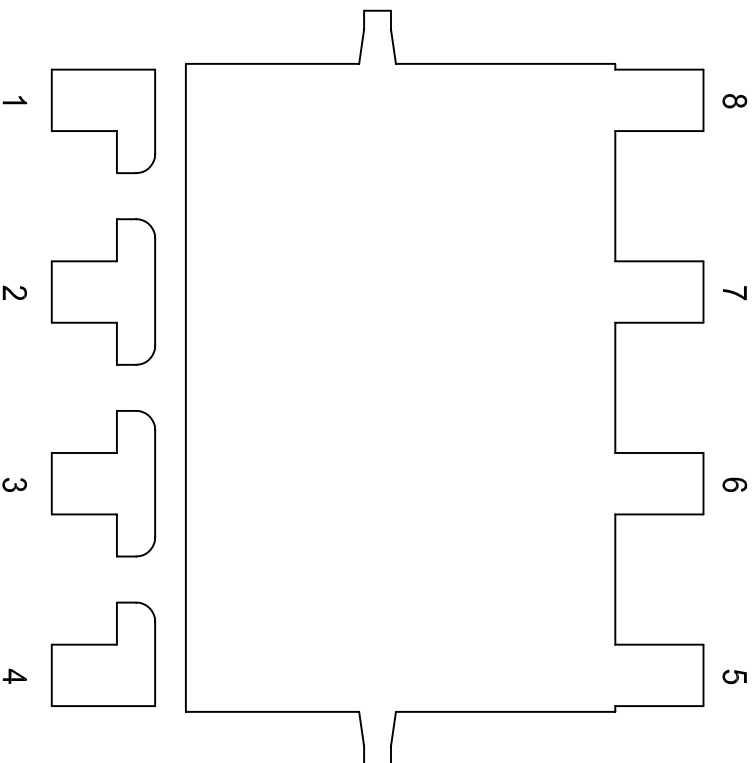
112x169 mils

MARKING INSTRUCTION

TOP :	BOTTOM :
-------	----------



n/a



Note: fused lead-to-pad (5, 6, 7, 8)

SPECIAL INSTRUCTIONS:

REF. BONDING DIAGRAM NO.	SCALE
	not to scale
DRAWN BY:	REVIEWED BY :

REVISION NO.		APPROVALS		
REV. #	DESCRIPTION	PCN #	DEPT	DATE
			CUST	
			QSM	
			QC	
			MFG	